

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSP170P H6327	**Issued**	4. February 2020
MA#	MA001623316		
Package	PG-SOT223-4-21	**Weight***	113.69 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.020	0.02		175	
	noble metal	gold	7440-57-5	0.077	0.07		679	
	inorganic material	silicon	7440-21-3	0.875	0.77	0.86	7700	8554
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		446	
	non noble metal	chromium	7440-47-3	0.152	0.13		1338	
	non noble metal	copper	7440-50-8	50.489	44.41	44.59	444094	445967
wire	non noble metal	copper	7440-50-8	0.091	0.08	0.08	798	798
encapsulation	organic material	carbon black	1333-86-4	0.599	0.53		5273	
	plastics	epoxy resin	-	8.992	7.91		79094	
	inorganic material	silicondioxide	60676-86-0	50.356	44.29	52.73	442925	527292
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12877	12877
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4512	4512
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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